

FIG. 1

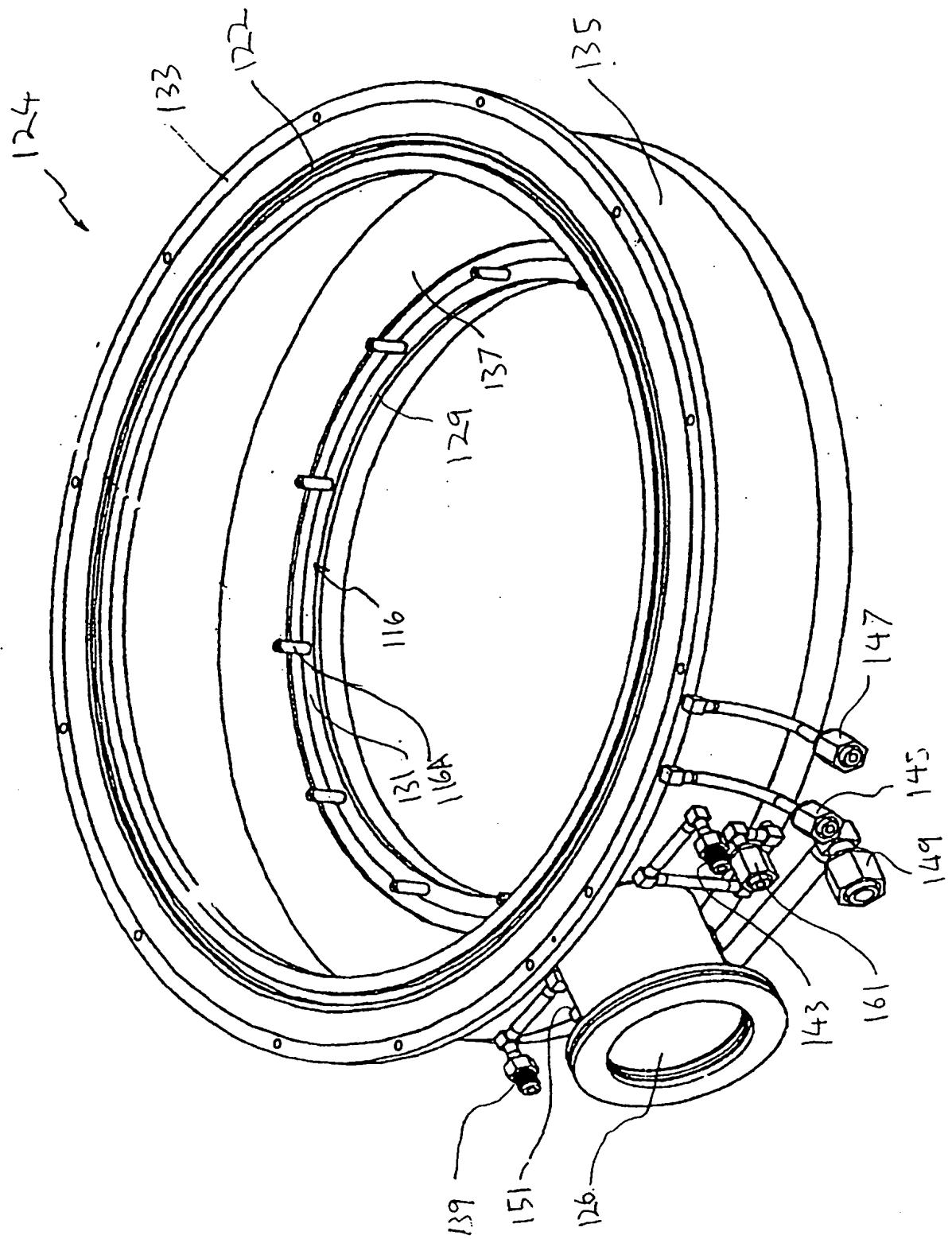
**10/521619**

FIG. 2

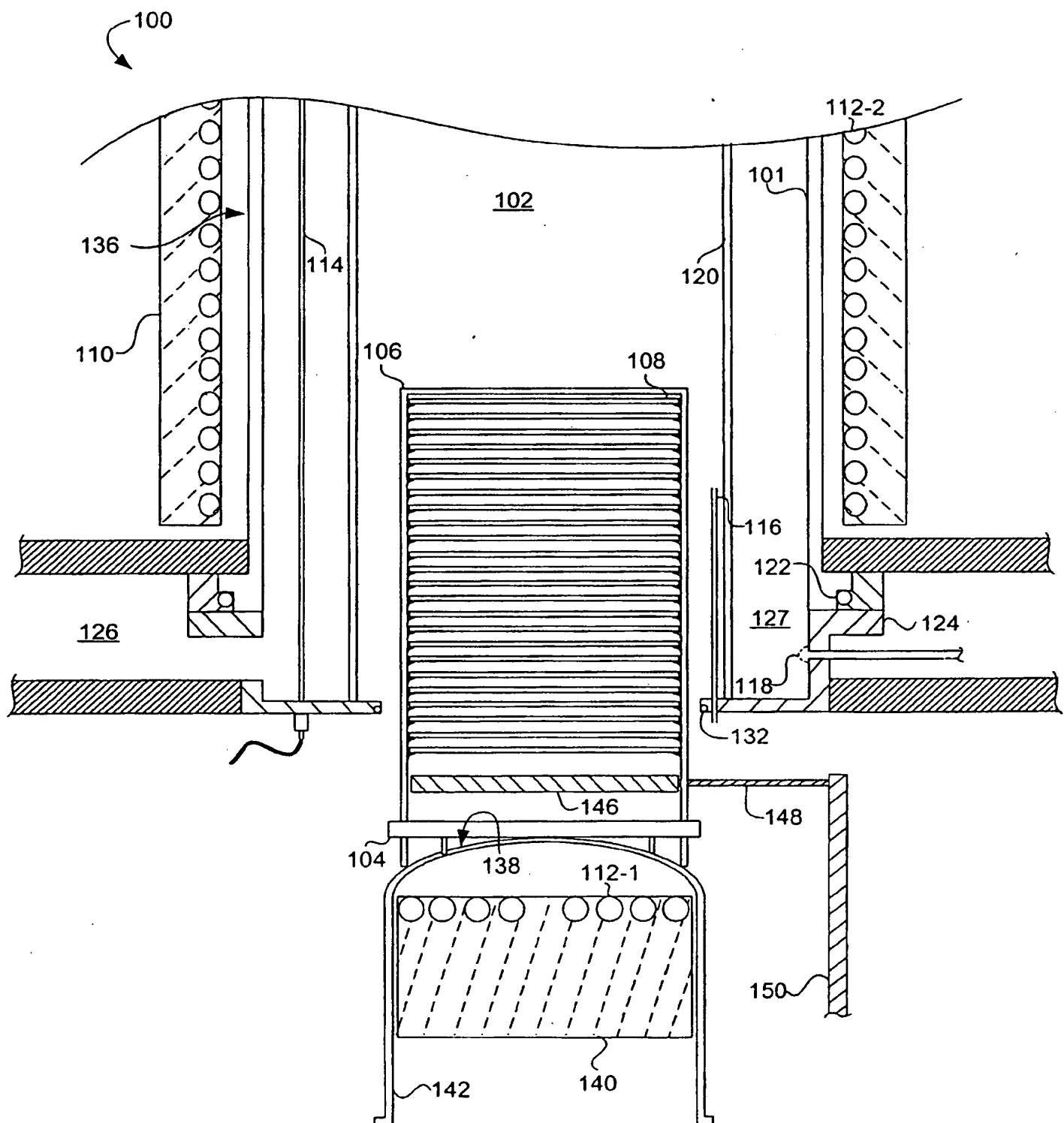


FIG. 3

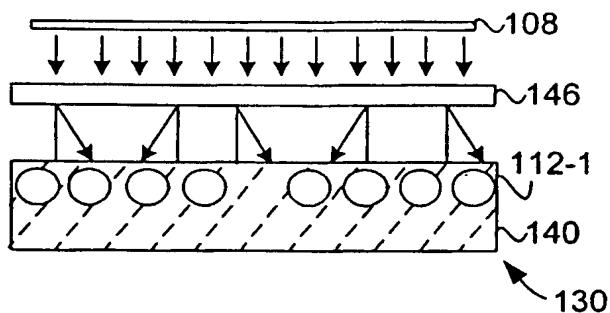


FIG. 4

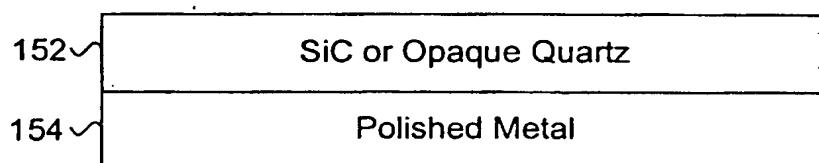


FIG. 5

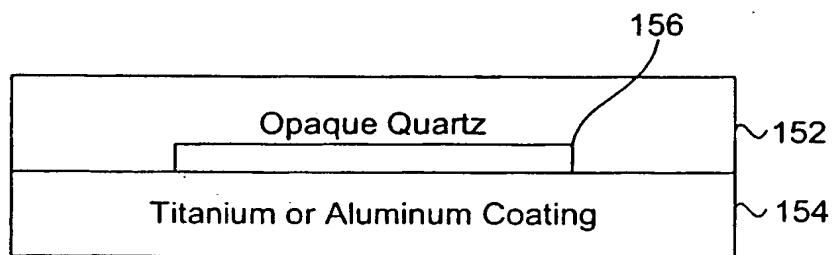
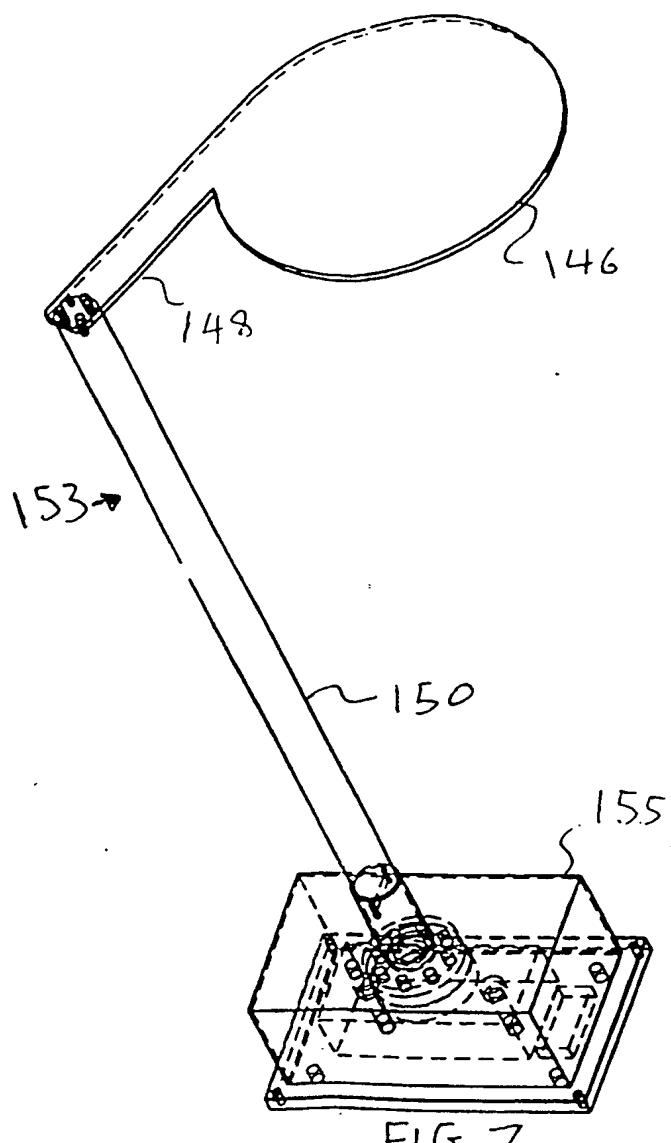


FIG. 6



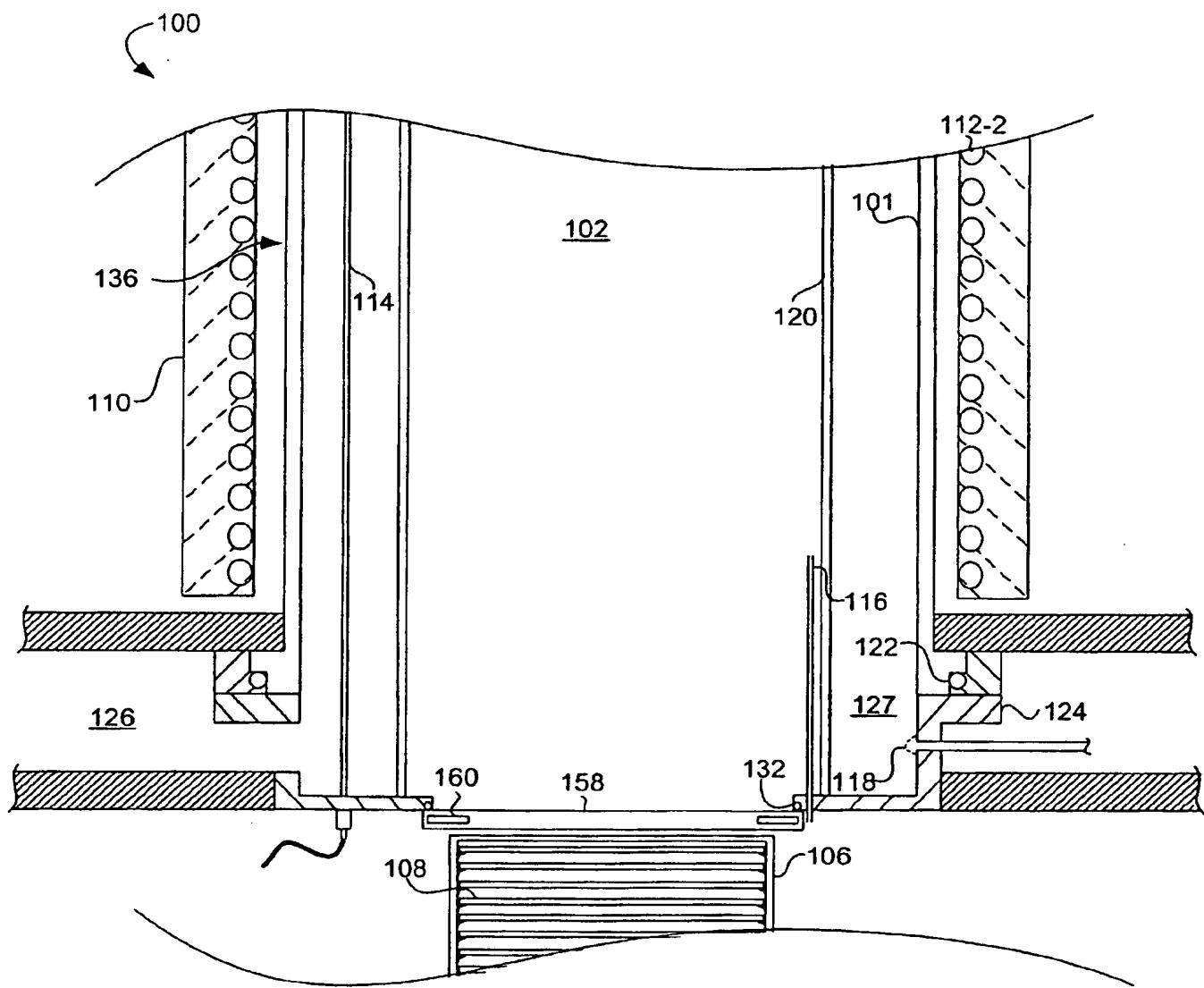


FIG. 8

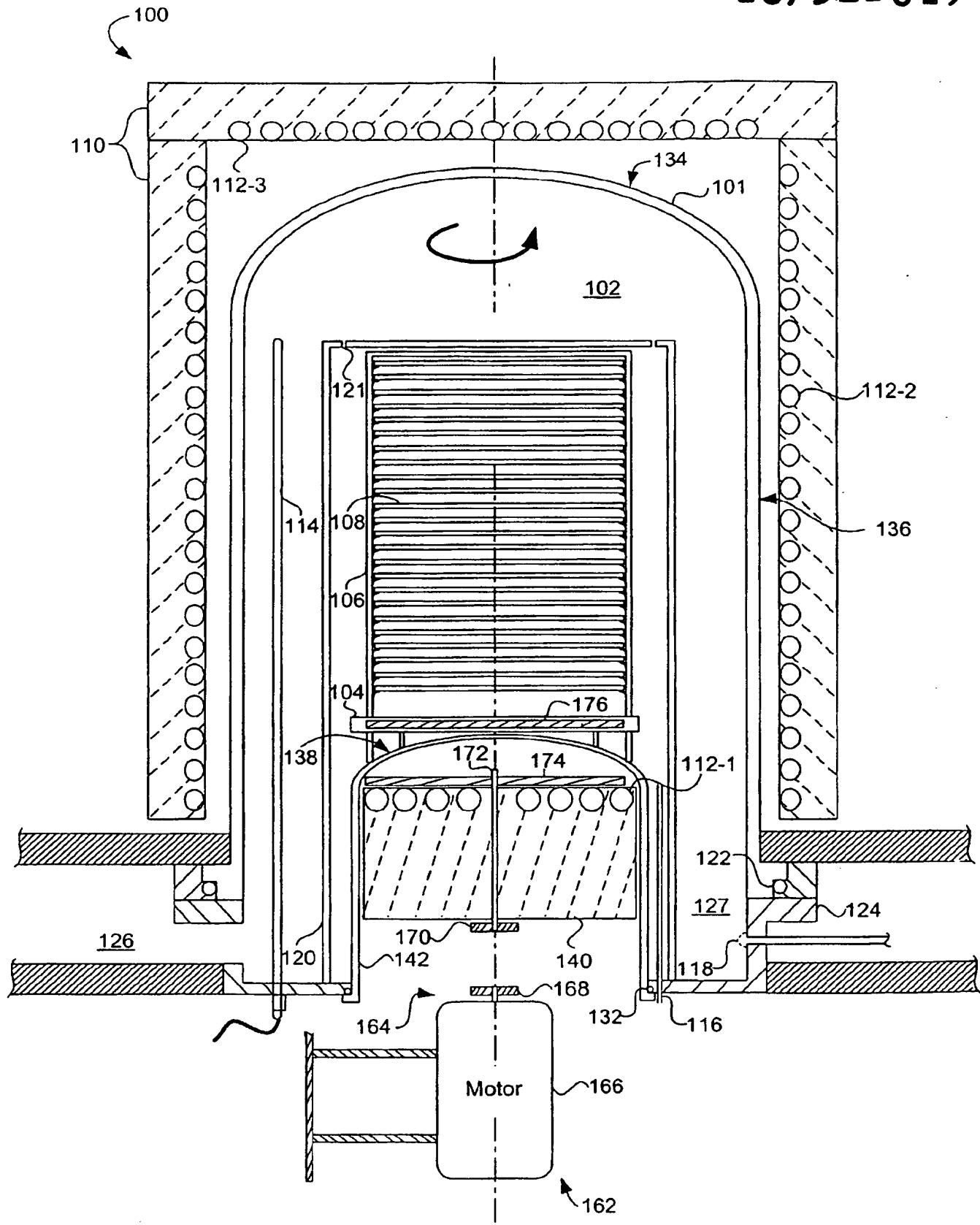


FIG. 9

10/521619

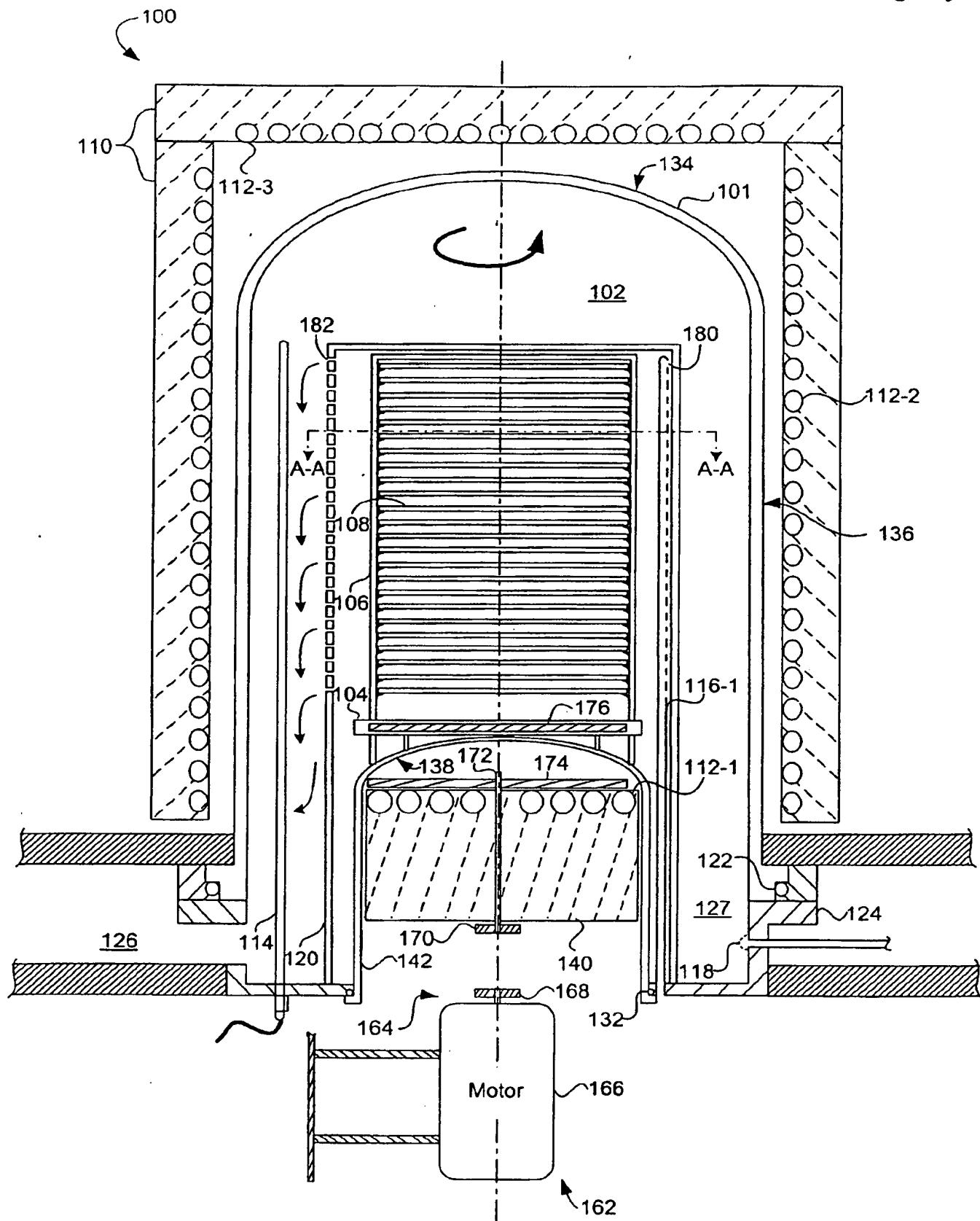


FIG. 10

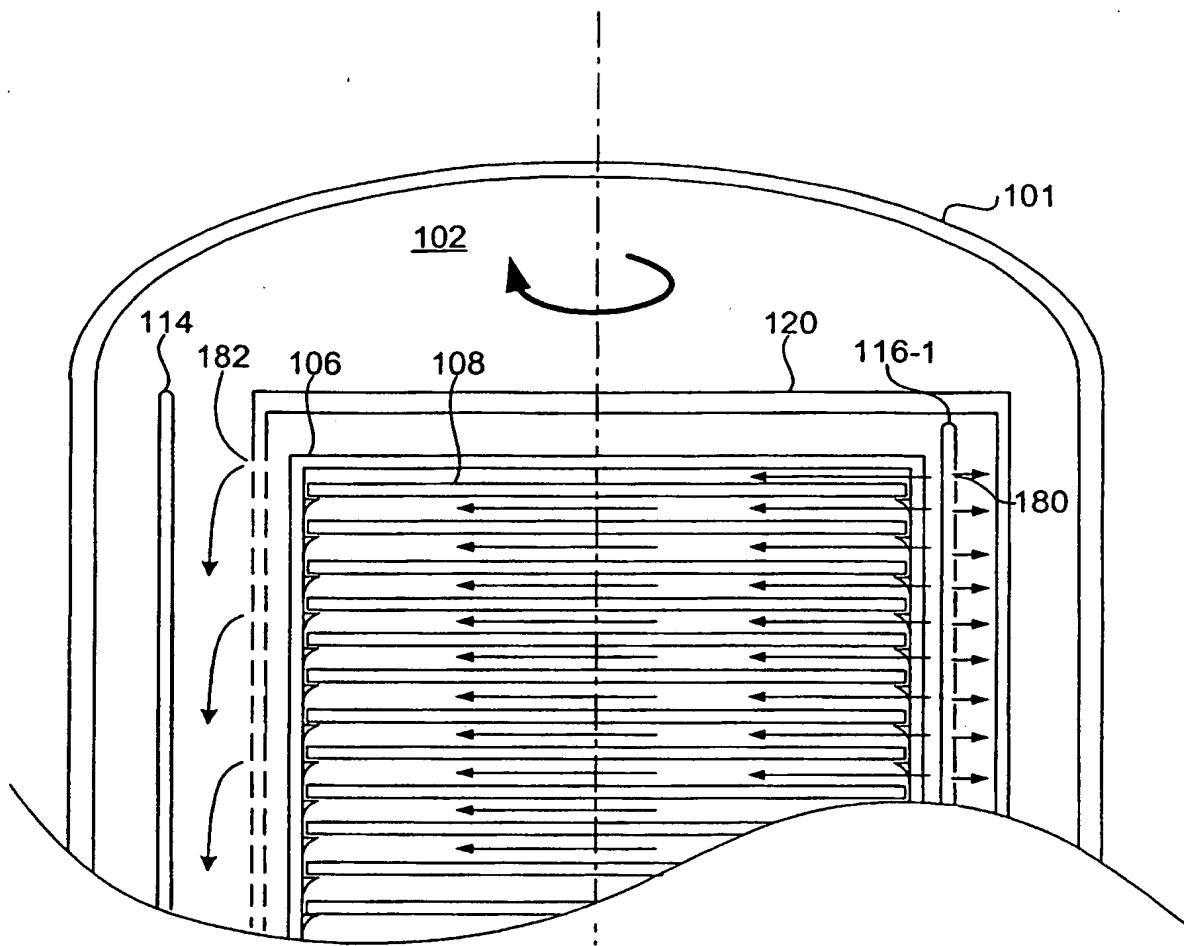


FIG. 11

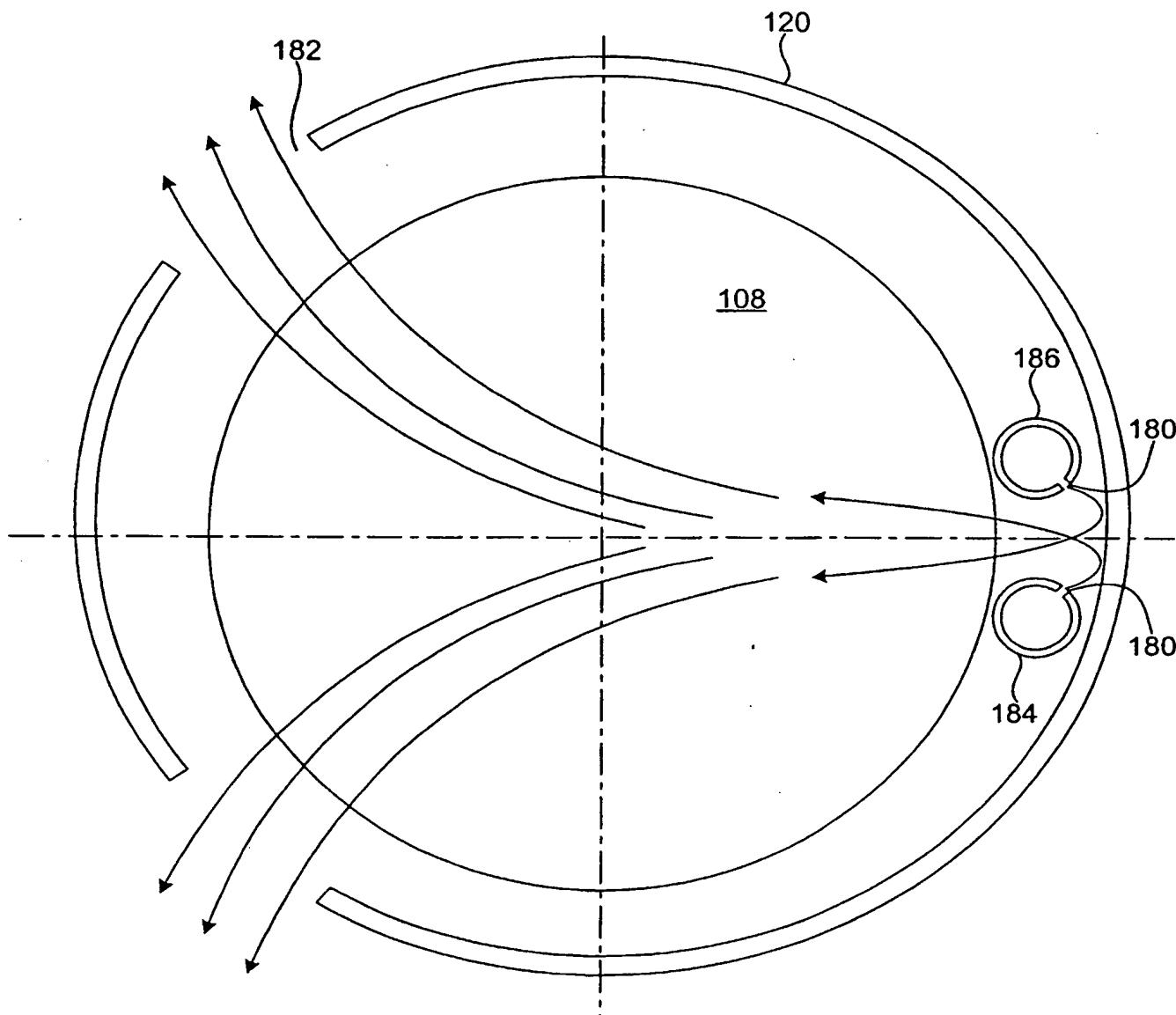


FIG. 12

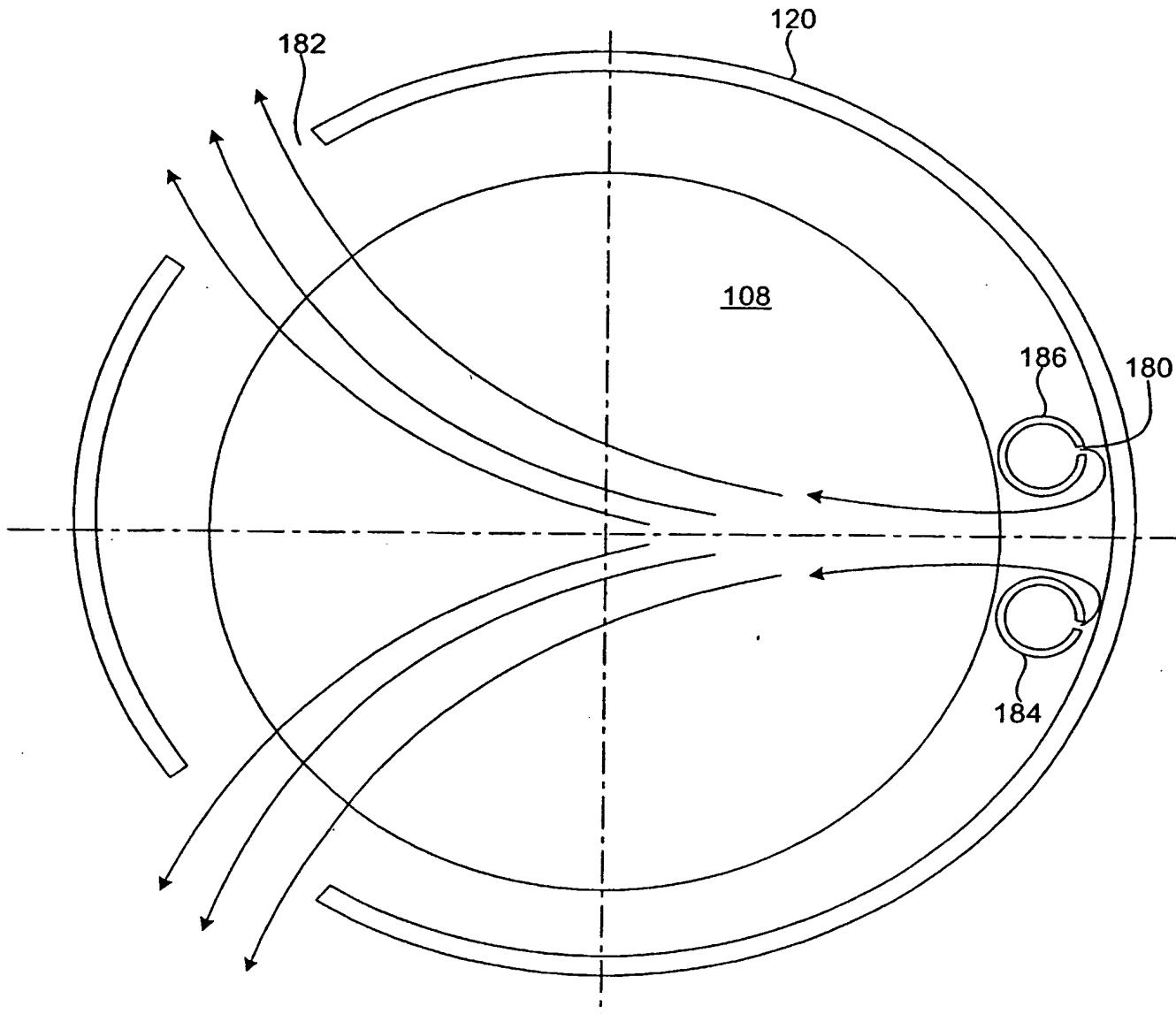


FIG. 13

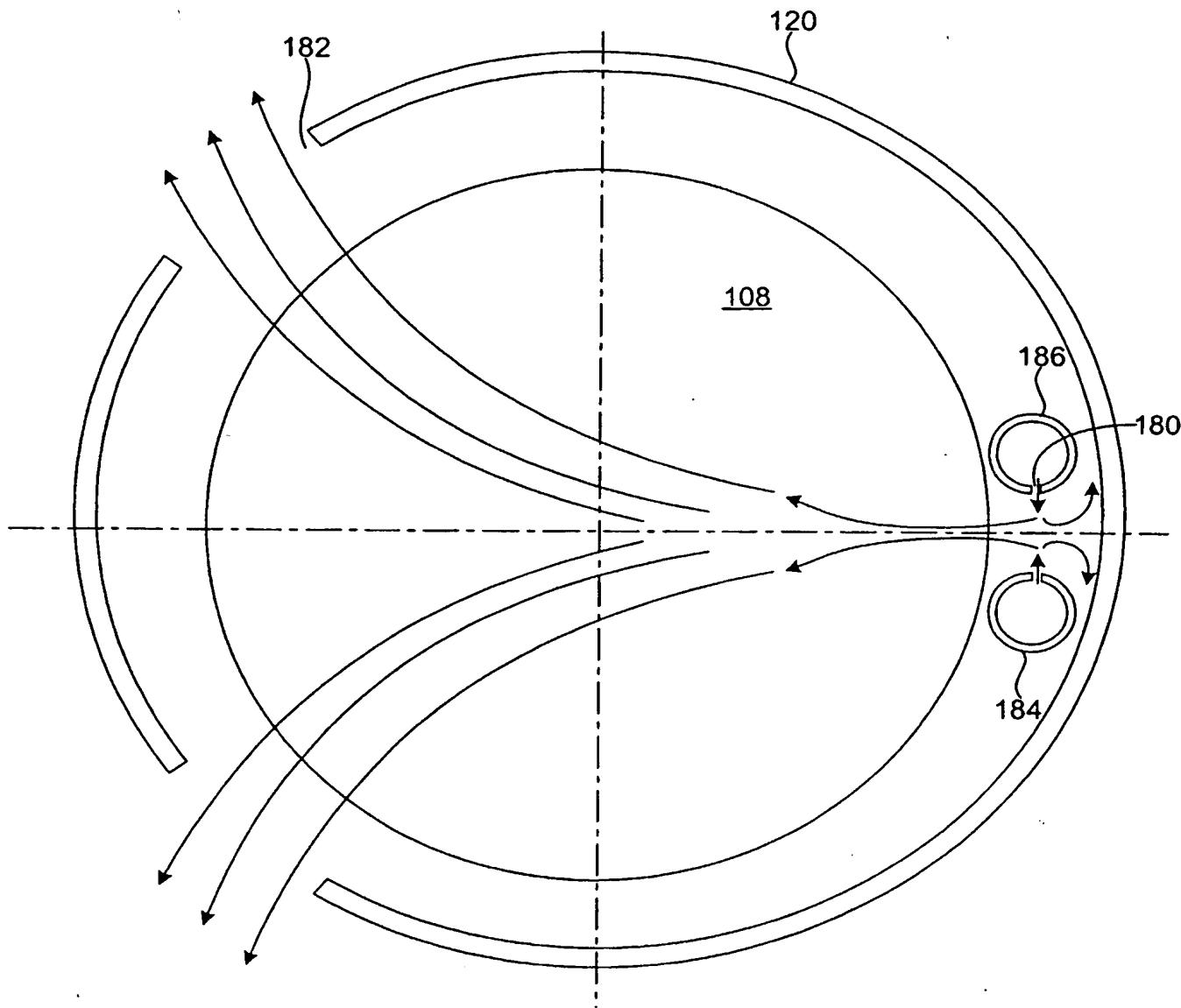


FIG. 14

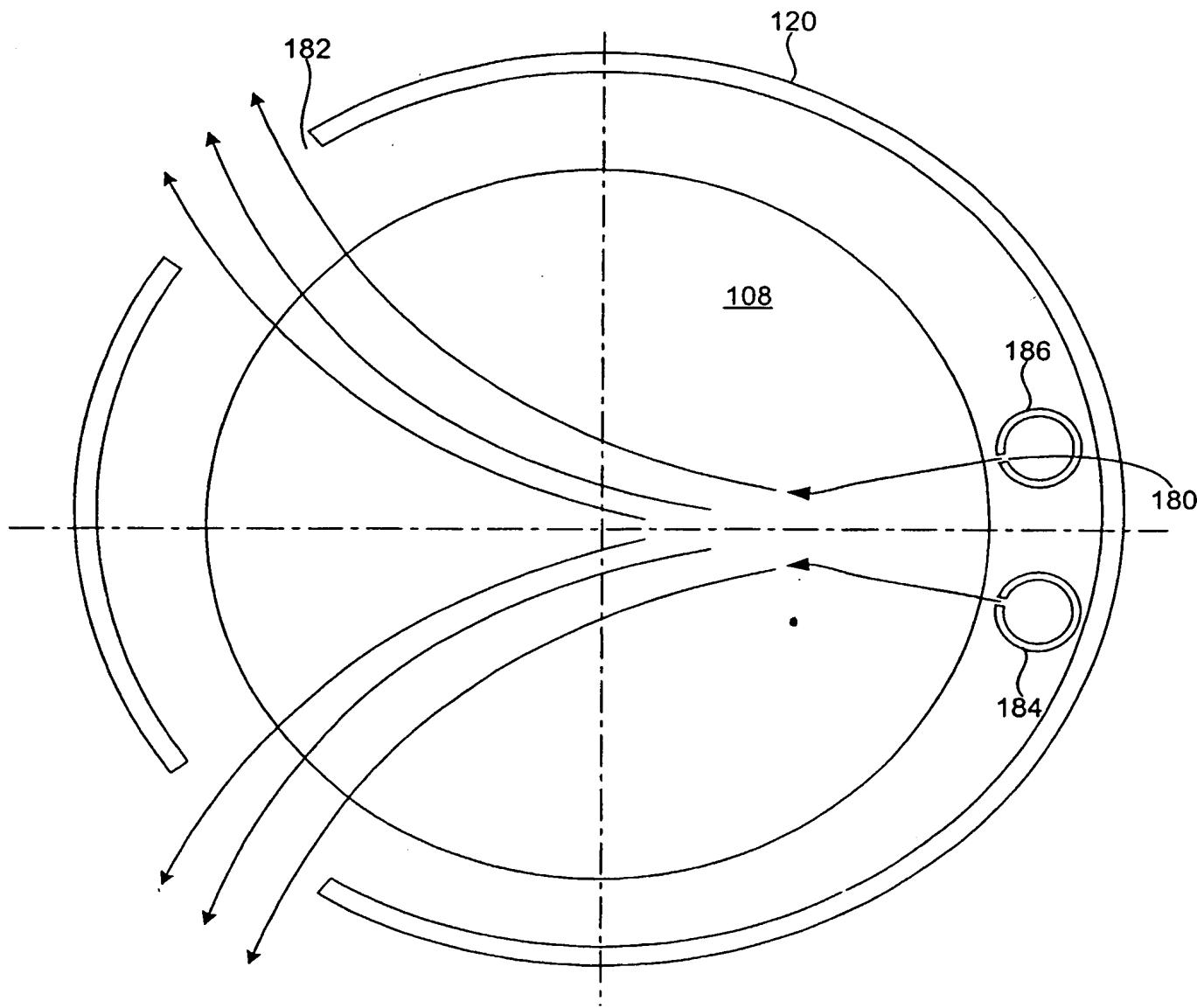


FIG. 15

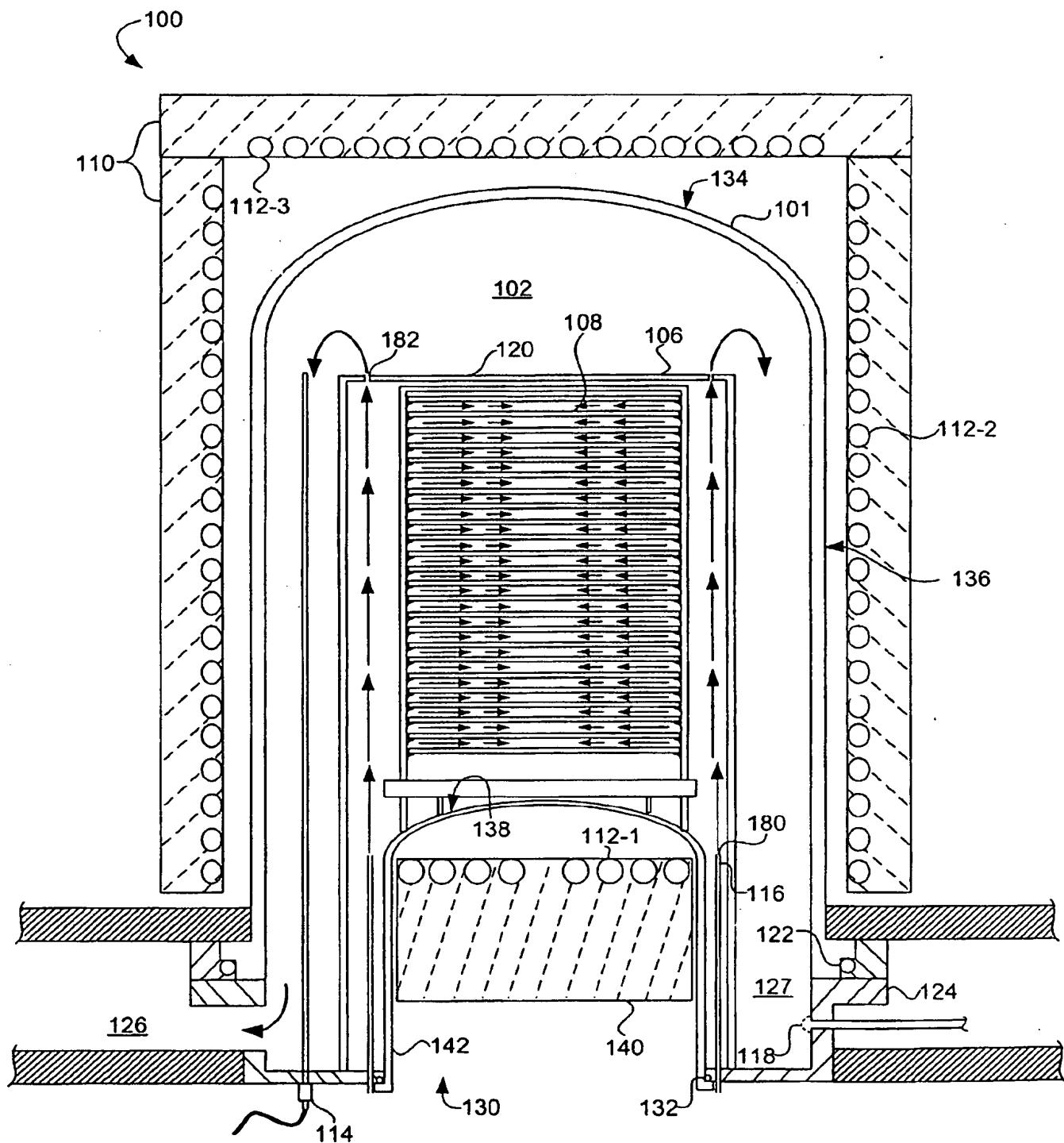


FIG. 16

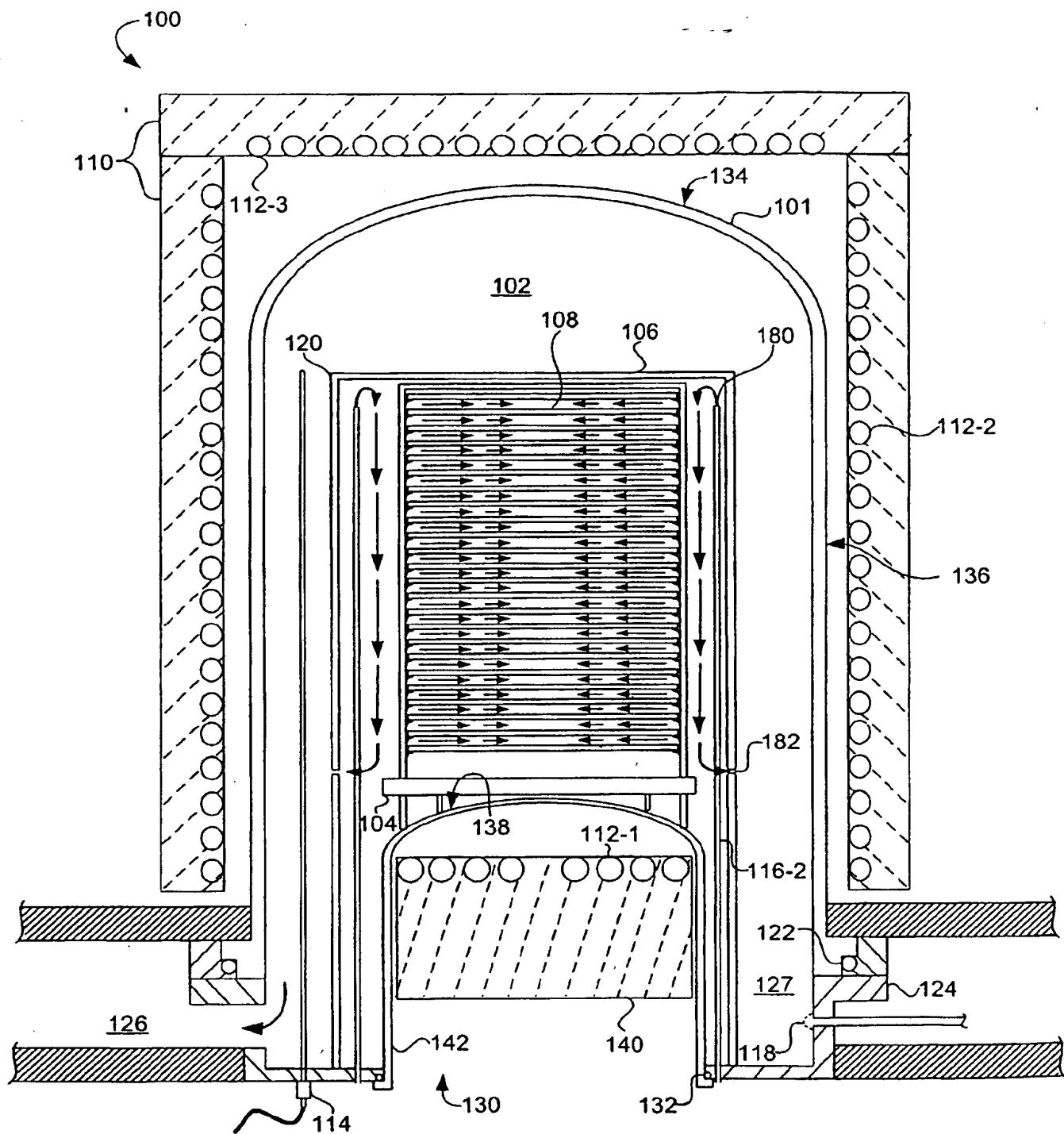


FIG. 17

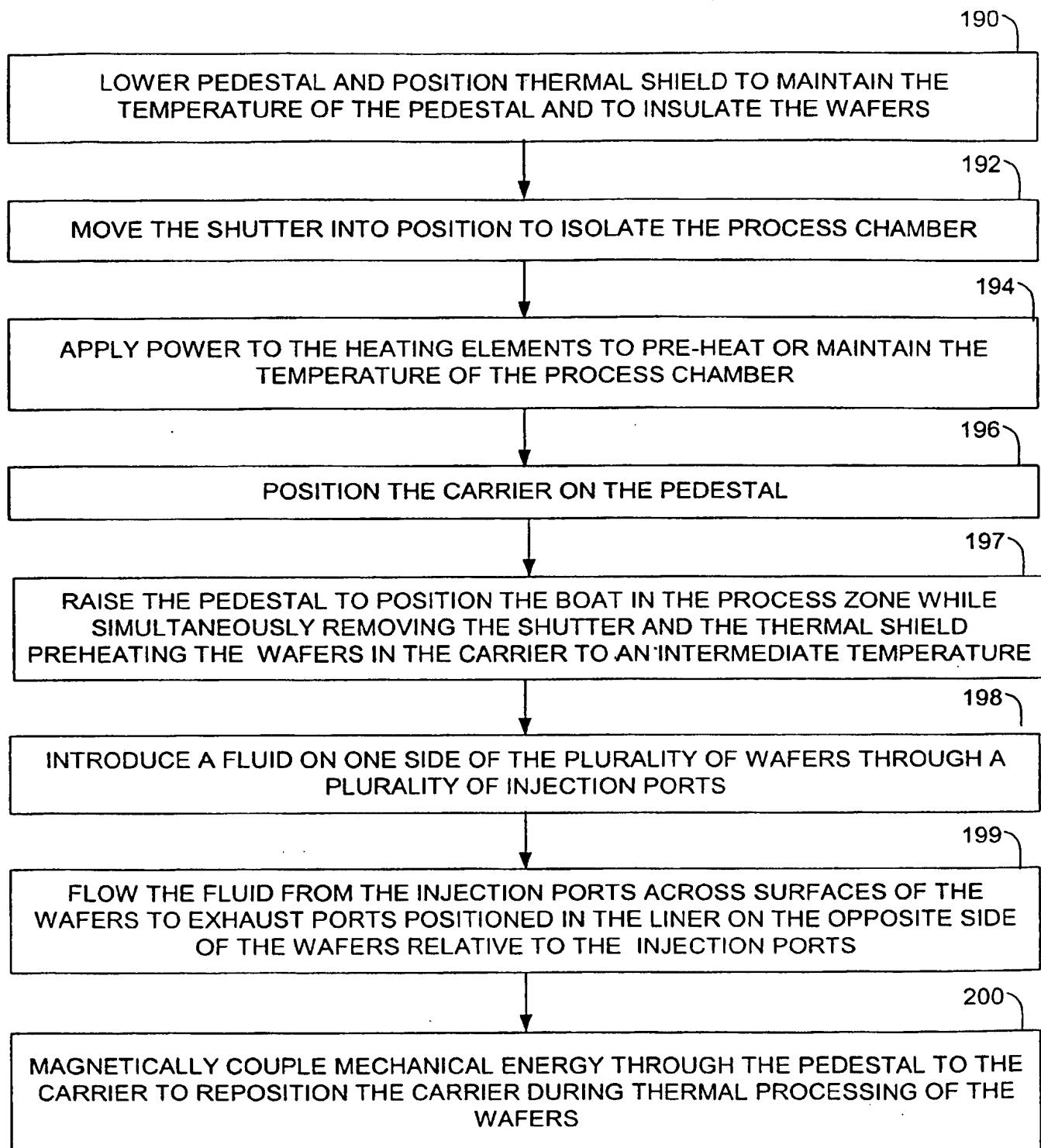


Fig. 18

202

Providing An Apparatus Having A Process Chamber No Larger Than Necessary To Accommodate The Carrier With The Wafers Held Therein

204

Heating The Process Chamber To Provide A Process Zone Therein Having A Substantially Isothermal Environment At A Desired Temperature

206

Lowering The Pedestal

208

Moving The Thermal Shield Into A Position To Reflect Heat From The Heating Element Back To The Pedestal To Maintain The Temperature Thereof

210

Moving The Shutter To Isolate The Process Chamber And Maintain The Temperature Thereof

212

Positioning The Carrier On The Pedestal

214

Moving The Thermal Shield

216

Preheating The Wafers In The Carrier To An Intermediate Temperature While Simultaneously Raising The Pedestal To Position The Carrier In The Process Zone

218

Positioning The Carrier In The Process Zone To Thermally Process The Wafers

220

Introducing A Fluid On One Side Of Wafers Through Injection Ports Positioned Relative Thereto

222

Flowing The Fluid Directly Across Surfaces Of The Wafers From The Injection Ports To Exhaust Ports In The Chamber Liner

224

Magnetically Coupling Mechanical Energy Through The Pedestal To The Carrier To Reposition The Carrier During Thermal Processing Of The Wafers

Fig. 19